

L Number	Hits	Search Text	DB	Time stamp
	2	6133637.pn..	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/12/06 11:57
	0	257/678,690,639,704	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/02/07 15:31
	11564	(257/678-704).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/02/07 15:31
	897010	((("257/678-704").CCLS.) and cover or lid or enclose\$	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/02/07 15:34
	467	((("257/678-704").CCLS.) and 257/737	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/02/07 15:34
	207098	((("257/678-704").CCLS.) and 257/737) and cover or lid	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/02/07 15:35
	9	((("257/678-704").CCLS.) and 257/737) and plastic adj body	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/02/07 15:50
	1	((("257/678-704").CCLS.) and 257/737) and plastic adj body and base	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/02/07 15:49
	0	((("257/678-704").CCLS.) and 257/737) and plastic adj body and air adj gap	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/02/07 15:52
	22854	(257/678-737).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/02/07 15:53
	5723	((("257/678-737").CCLS.) and substrate and (cover or lead or enclose\$)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/02/07 15:54
	6	(((("257/678-737").CCLS.) and substrate and (cover or lead or enclose\$)) and lead and expose\$ adj portion) and air adj gap	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/02/07 15:56
	2	(((("257/678-737").CCLS.) and substrate and (cover or lead or enclose\$)) and lead and expose\$ adj portion) and plastic adj body	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/02/07 15:57
	189	((("257/678-737").CCLS.) and substrate and (cover or lead or enclose\$)) and lead and expose\$ adj portion	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/02/07 16:27

	1210	257/704	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/02/07 16:27
	1	257/704 and bump and air adj gap	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/02/07 16:31
	2	(257/704 and bump) and exposed adj portion same lead	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/02/07 16:32
	118	257/704 and bump	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/02/07 16:47
	0	5311402.pn	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/02/07 16:47
	3	5188280.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/02/07 16:57
	3	5311402.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/02/07 16:57
	1716	(glass near (lid cover substrate)) near3 plastic	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/06 12:01
	107	((glass near (lid cover substrate)) near3 plastic) and ((charge adj coupled adj device) ccd)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/12/06 12:03
	19	(glass near lid) near3 plastic	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/09 07:53
	1935	(glass near (lid cover substrate) near3 plastic)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/09 07:53
	21	(glass near lid) near3 plastic	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/09 08:08
	9	semiconductor and (glass near body) near3 plastic	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/09 08:08
	590	((glass near (lid cover substrate) near3 plastic)) and semiconductor	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/09 08:30

